2SJ484

Silicon P-Channel MOS FET High Speed Power Switching

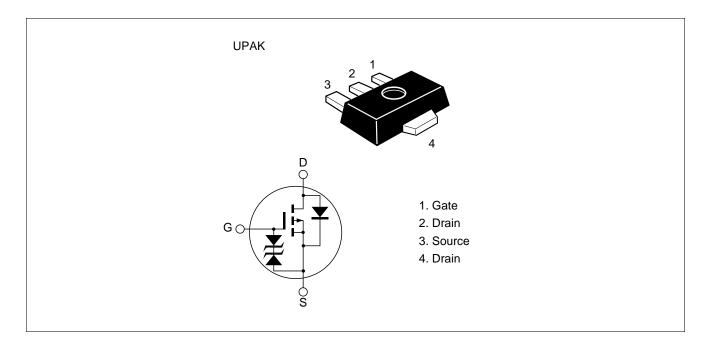
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ADE-208-501 A 2nd. Edition

Features

- Low on-resistance $R_{\rm DS(on)} = 0.18~\Omega~typ.~(at~V_{\rm GS} = -10V,~I_{\rm D} = -1A)$
- Low drive current
- High speed switching
- 4V gate drive devices.

Outline





2SJ484

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-30	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-2	А	
Drain peak current	I _{D(pulse)} *1	-4	А	
Body to drain diode reverse drain current	I _{DR}	-2	А	
Channel dissipation	Pch*2	1	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW ≤ 100µs, duty cycle ≤ 10 %

2. When using aluminium ceramic board (12.5 x 20 x 0.7 mm)

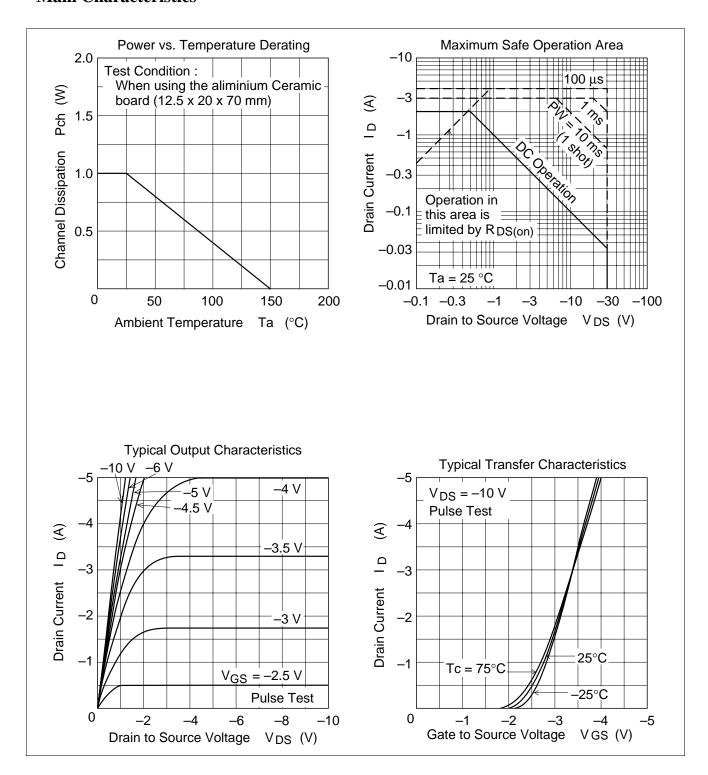
Electrical Characteristics ($Ta = 25^{\circ}C$)

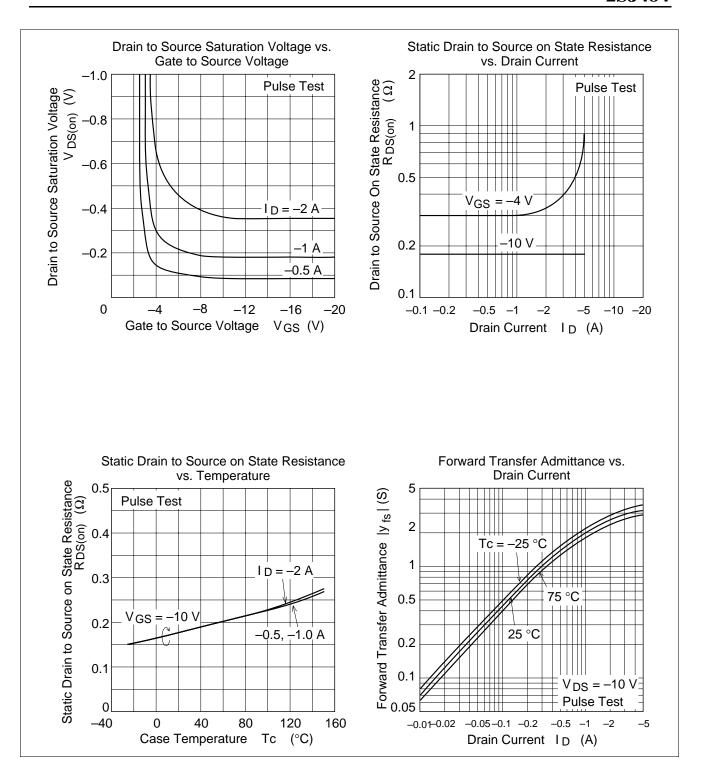
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	_	_	V	$I_{D} = -10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-10	μА	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{D} = -1 \text{mA}, V_{DS} = -10 \text{V}$
Static drain to source on state resistance	R _{DS(on)}	_	0.18	0.23	Ω	$I_D = -1A, V_{GS} = -10V^{*1}$
	R _{DS(on)}	_	0.3	0.45	Ω	$I_D = -1A, V_{GS} = -4V^{*1}$
Forward transfer admittance	y _{fs}	1.2	2.0	_	S	$I_D = -1A, V_{DS} = -10V^{*1}$
Input capacitance	Ciss	_	230	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	140	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	50	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	10	_	ns	$I_D = -1A$, $R_L = 30\Omega$
Rise time	t _r	_	30	_	ns	$V_{GS} = -10V$
Turn-off delay time	t _{d(off)}	_	35	_	ns	
Fall time	t _f	_	30	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-0.95	_	V	$I_F = -2A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	60	_	ns	$I_F = -2A, V_{GS} = 0$ diF/ dt = 50A/µs

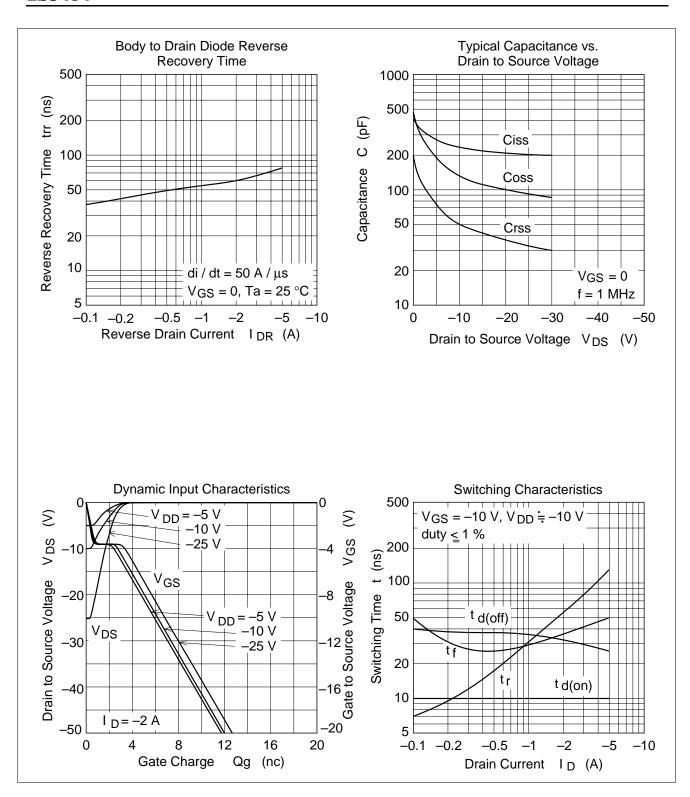
Notes: 1. Pulse test

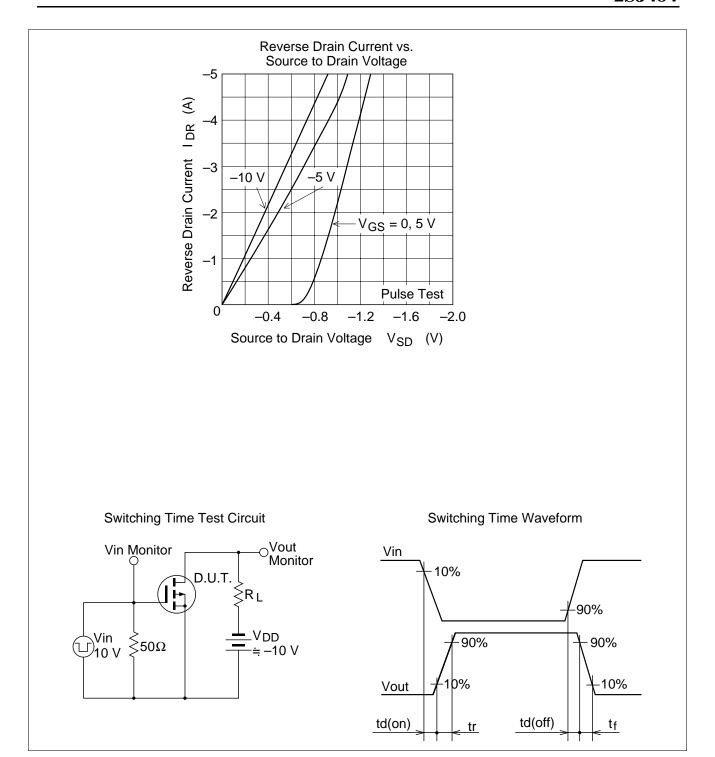
2. Marking is "WY".

Main Characteristics



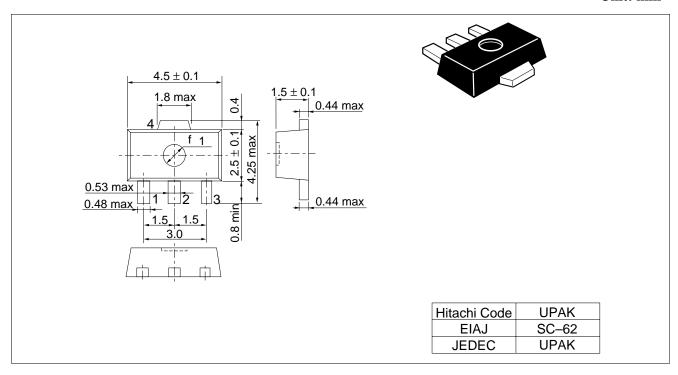






Package Dimensions

Unit: mm



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